

## PATENT ASSIGNMENT

Electronic Version v1.1  
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	Release of Security Interest in Patents
CONVEYING PARTY DATA	
Name	Execution Date
Wells Fargo Bank, National Association	11/08/2012
RECEIVING PARTY DATA	
Name:	Handy & Harman Electronic Materials Corporation
Street Address:	1133 Westchester Avenue, Suite N222
City:	White Plains
State/Country:	NEW YORK
Postal Code:	10604
PROPERTY NUMBERS Total: 4	
Property Type	Number
Application Number:	10015500
Application Number:	60399449
Patent Number:	5853557
Patent Number:	5667659
CORRESPONDENCE DATA	
Fax Number:	3026365454
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	202-408-3121 x2348
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Address Line 4:	Washington, DISTRICT OF COLUMBIA 20005
ATTORNEY DOCKET NUMBER:	422092-24
NAME OF SUBMITTER:	Jean Paterson
Total Attachments: 5	

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RECORDATION FORM COVER SHEET  
PATENTS ONLY

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of conveying party(ies)

Wells Fargo Bank, National Association

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance/Execution Date(s):

Execution Date(s) November 8, 2012

- ☐ Assignment ☐ Merger  
☐ Security Agreement ☐ Change of Name  
☐ Joint Research Agreement  
☐ Government Interest Assignment  
☐ Executive Order 9424, Confirmatory License  
☒ Other Release of Security Interest in Patents

2. Name and address of receiving party(ies)

Name: Handy & Harman Electronic Materials Corporation

Internal Address: 1133 Westchester Avenue, Suite N222

Street Address:

City: White Plains

State: NY

Country: USA Zip: 10604

Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application or patent number(s):

☐ This document is being filed together with a new application.

A. Patent Application No.(s)

See Schedule A

B. Patent No.(s)

See Schedule A

Additional numbers attached? ☒ Yes ☐ No

5. Name and address to whom correspondence concerning document should be mailed:

Name: Elaine Carrera, Legal Assistant

Internal Address: Cahill Gordon & Reindel LLP

Street Address: 80 Pine Street

City: New York

State: NY Zip: 10005

Phone Number: (212) 701-3365

Docket Number:

Email Address: ecarrera@cahill.com

6. Total number of applications and patents involved: 4

7. Total fee (37 CFR 1.21(h) & 3.41) \$

- ☐ Authorized to be charged to deposit account  
☐ Enclosed  
☐ None required (government interest not affecting title)

8. Payment Information

Deposit Account Number

Authorized User Name

9. Signature:

Elaine Carrera  
Signature

November 12, 2012

Date

Elaine Carrera

Name of Person Signing

Total number of pages including cover sheet, attachments, and documents:

5

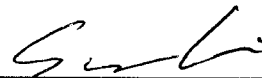
Documents to be recorded (including cover sheet) should be faxed to (571) 273-0140, or mailed to:  
Mail Stop Assignment Recordation Services, Director of the USPTO, P.O.Box 1450, Alexandria, V.A. 22313-1450

RELEASE OF SECURITY INTEREST IN PATENTS

KNOW ALL MEN BY THESE PRESENTS, that WELLS FARGO BANK, NATIONAL ASSOCIATION, a national banking association, successor by merger to Wachovia Bank, National Association, a national banking association, successor by merger to Congress Financial Corporation, a Delaware corporation, in its capacity as agent (hereinafter referred to as "Secured Party"), having an office at 100 Park Avenue, New York, New York 10017, DOES HEREBY CERTIFY that the security interest it holds in those certain patents, as set forth in Schedule "A" attached hereto (the "Patents"), of HANDY & HARMAN ELECTRONIC MATERIALS CORPORATION, a Florida corporation, having a place of business at 1133 Westchester Avenue, Suite N222, White Plains, New York 10604 ("Debtor"), pursuant to the Patent Collateral Assignment and Security Agreement, dated March 31, 2004, between Debtor and Secured Party, recorded on May 26, 2004, with the U.S. Patent and Trademark Office at Reel 015355, Frame 0918 (the "Security Agreement"), is released and all interests in the Patents, and any related property, previously pledged to Secured Party under the Security Agreement are hereby released to Debtor, without representation, warranty or recourse of any kind, nature or description.

IN WITNESS WHEREOF, Secured Party has caused this Release of Security Interest in Patents to be executed by its duly authorized officer this 8<sup>th</sup> day of November 2012.

WELLS FARGO BANK, NATIONAL  
ASSOCIATION, as Agent

By:   
Name: Sang Kim  
Title: Vice President

STATE OF NEW YORK     )  
  ) ss.:  
COUNTY OF NEW YORK    )

On the 8 day of November, 2012, before me personally came Sang Kim, to me known, who being by me duly sworn, did depose and say, that he is an Authorized Signatory of WELLS FARGO BANK, NATIONAL ASSOCIATION and that said instrument was signed on behalf of such national banking association by authority of its Board of Directors, and he acknowledged said instrument to be the free act of deed of said association.



Notary Public

**MARIA CAMACHO**  
**NOTARY PUBLIC-STATE OF NEW YORK**  
**No. 01CA5086952**  
**Qualified in Nassau County**  
**Certificate Filed in New York County**  
**My Commission Expires October 27, 2013**

SCHEDULE A  
TO  
RELEASE OF SECURITY INTERESTS IN PATENTS

List of Patents and Patent Applications

Patent Description	Patent Number	Registration Date	Expiration Date	Patent Application	Application/Serial Number	Application Date
Barrier Layer for Electrical Connectors and Methods of Applying the Layer – USA					10/015,500	12/11/01
Laminar Heatsink Fabrication Method – USA					60/399,449	07/29/02
Low Friction, Ductile, Multilayer Electrodeposits (CIP of 08/627,542 – Patent No. 5,667,659) – USA	5853557	12/29/98			08/833009	04/04/97
Low Friction, Ductile, Multilayer Electrodeposits (PCT application corresponds to U.S. 08/627542 – Patent No. 5667659 <u>and</u> additional material contained in U.S. 08833009 – Patent No. 5853557, which is a CIP of U.S. 08/627542 – Patent					PCT/US97/05559	04/04/97

